



日月光半導體 2014 第二季法人說明會

Presented by

吳田玉
營運長

July 30, 2014



免責聲明



This presentation contains "forward-looking statements" within the meaning of Section 27A of the United States Securities Act of 1933, as amended, and Section 21E of the United States Securities Exchange Act of 1934, as amended, including statements regarding our future results of operations and business prospects. Although these forward-looking statements, which may include statements regarding our future results of operations, financial condition or business prospects, are based on our own information and information from other sources we believe to be reliable, you should not place undue reliance on these forward-looking statements, which apply only as of the date of this press release. The words "anticipate," "believe," "estimate," "expect," "intend," "plan" and similar expressions, as they relate to us, are intended to identify these forward-looking statements in this press release. Our actual results of operations, financial condition or business prospects may differ materially from those expressed or implied in these forward-looking statements for a variety of reasons, including risks associated with cyclicity and market conditions in the semiconductor or electronic industry; changes in our regulatory environment, including our ability to comply with new or stricter environmental regulations and to resolve environmental liabilities; demand for the outsourced semiconductor packaging, testing and electronic manufacturing services we offer and for such outsourced services generally; the highly competitive semiconductor or manufacturing industry we are involved in; our ability to introduce new technologies in order to remain competitive; international business activities; our business strategy; our future expansion plans and capital expenditures; the strained relationship between the Republic of China and the People's Republic of China; general economic and political conditions; the recent global economic crisis; possible disruptions in commercial activities caused by natural or human-induced disasters; fluctuations in foreign currency exchange rates; and other factors. For a discussion of these risks and other factors, please see the documents we file from time to time with the Securities and Exchange Commission, including our 2013 Annual Report on Form 20-F filed on April 17, 2014.

日月光2014上半年度營運概況



- 日月光2014上半年度合併營收年成長率達到15%
 - 半導體封裝測試2014第二季營收創歷史新高（季營收成長率達14%）

- K7廠最新消息

- 系統級封裝最新消息
 - 宏觀角度
 - 具體實例
 - 技術建構基礎

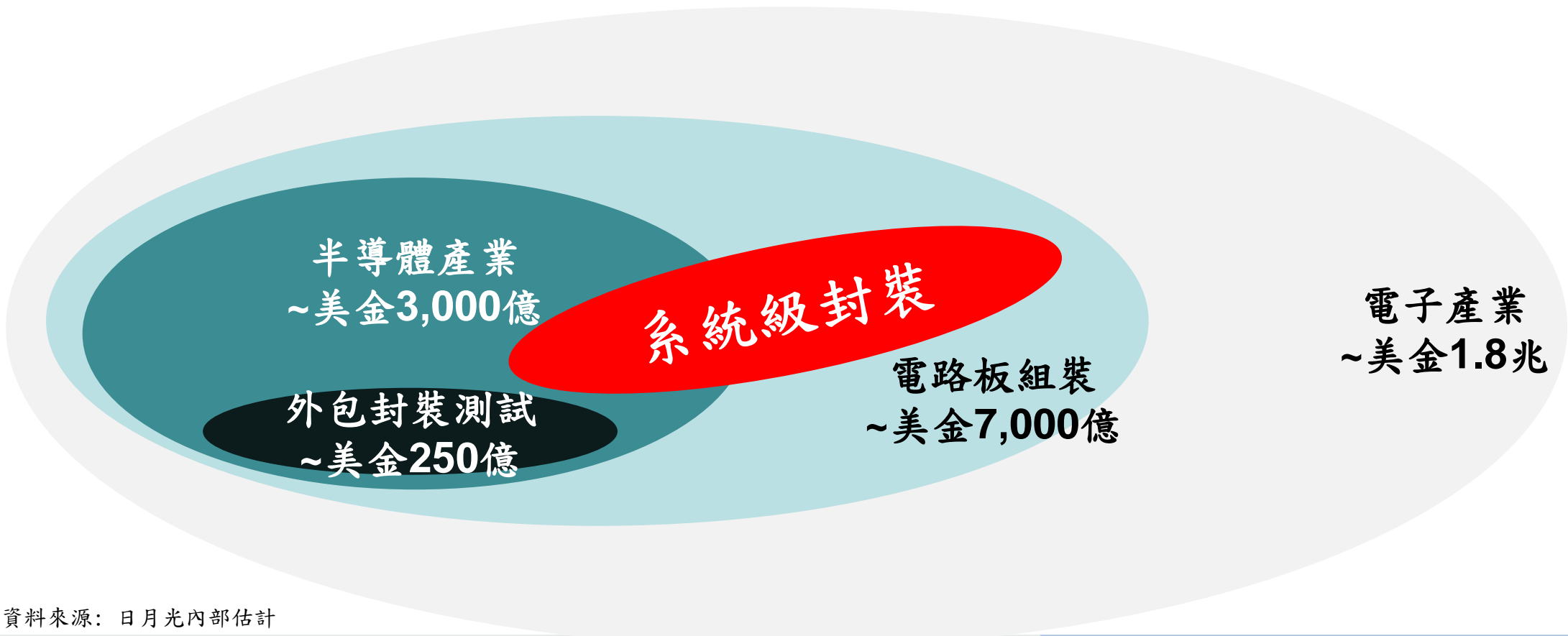
註：營收季或年成長率均按照新台幣營收數字計算

系統級封裝：半導體產業中的新興市場



ASE GROUP

- 身為擁有特殊技術和生產專業的系統整合商，日月光在快速成長的系統級封裝市場將占有領導地位



資料來源：日月光內部估計

系統級封裝：系統級整合方案



ASE GROUP

- 日月光結合外包封裝測試及電子代工服務，創造企業本身在系統整合之競爭優勢



IC 設計商推動

OEM 系統商推動



封裝和系統級封裝：技術應用一覽

- 高整合
- 最佳化
- 微型化
- 簡單化

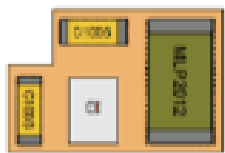
電源管理 - 電源管理單元



面積縮小63%



電源管理 - μ DC-DC 直流電源轉換器



面積縮小36%



移動/定位 感應器

3-axis accelerometer

3-axis accelerometer
3-axis magnetometer



功能性增加



連線裝置 - 低功耗藍芽



面積縮小88%



射頻/射頻前端 - 功率放大器



面積縮小44%



儲存裝置 - 固態硬碟



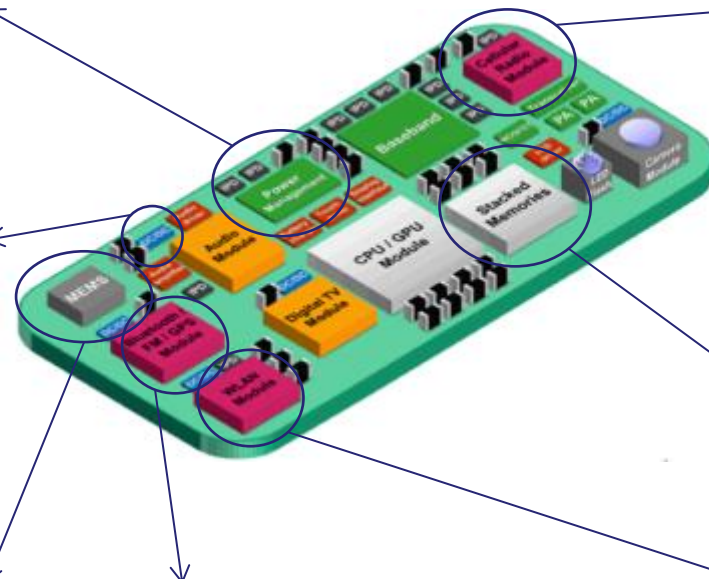
面積縮小79%



連線裝置 - 無線區域網

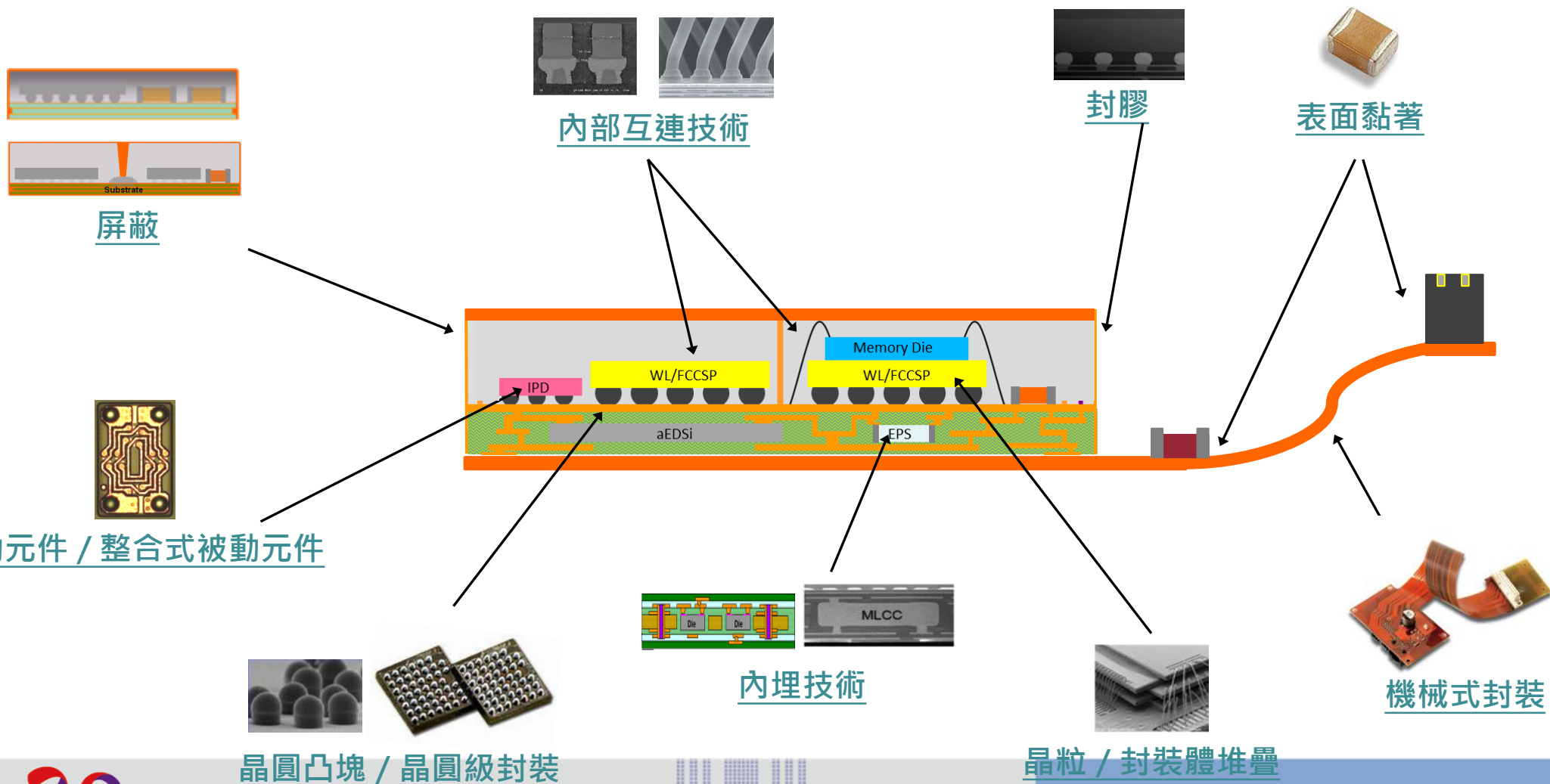


面積縮小47%



日月光系統級封裝技術服務

透過擁有核心技術，日月光在系統整合占有獨特競爭力



系統級封裝價值

- 市場趨勢：微小化，低耗電，成本，移動性
- 生產設計完整最佳化
 - 技術廣度及深度
 - 業界合作及知識
 - 系統設計及生意整合之一條龍服務
- 生產品質，周轉時間及規模可擴展性

謝謝

www.aseglobal.com



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日月光半導體 2014 第二季法人說明會

董宏思
財務長
日月光半導體
2014年7月30日



Safe Harbor Notice



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合併綜合損益表

與上一季比較

(未經會計師查核)



(新台幣百萬元)

營業收入淨額:

	Q2 / 2014	%	Q1 / 2014	%	季變化
封裝	30,641	52.3%	26,722	48.9%	15%
測試	6,600	11.3%	5,785	10.6%	14%
材料直接銷售	873	1.5%	779	1.4%	12%
電子代工服務	20,501	35.0%	21,365	39.1%	-4%
其它	0	0.0%	49	0.1%	-100%
營業收入淨額合計	58,615	100.0%	54,700	100.0%	7%
營業毛利	12,600	21.5%	10,349	18.9%	22%
營業淨利 (淨損)	6,600	11.3%	5,070	9.3%	30%
稅前淨利 (淨損)	6,050	10.3%	4,284	7.8%	41%
所得稅利益 (費用)	(818)	-1.4%	(727)	-1.3%	
非控制權益	(138)	-0.2%	(119)	-0.2%	
歸屬於本公司業主之淨利	5,094	8.7%	3,438	6.3%	48%
稀釋每股盈餘 (新台幣元)	0.64		0.44		45%
EBITDA	13,109	22.4%	11,363	20.8%	15%

合併綜合損益表

與去年同期比較

(未經會計師查核)



(新台幣百萬元)	Q2 / 2014	%	Q2 / 2013	%	年變化
營業收入淨額:					
封裝	30,641	52.3%	29,021	57.2%	6%
測試	6,600	11.3%	6,505	12.8%	1%
材料直接銷售	873	1.5%	759	1.5%	15%
電子代工服務	20,501	35.0%	14,186	27.9%	45%
其它	0	0.0%	289	0.5%	-100%
營業收入淨額合計	58,615	100.0%	50,760	100.0%	15%
營業毛利	12,600	21.5%	10,436	20.6%	21%
營業淨利 (淨損)	6,600	11.3%	5,403	10.6%	22%
稅前淨利 (淨損)	6,050	10.3%	5,038	9.9%	20%
所得稅利益 (費用)	(818)	-1.4%	(1,127)	-2.2%	
非控制權益	(138)	-0.2%	(91)	-0.2%	
歸屬於本公司業主之淨利	5,094	8.7%	3,820	7.5%	33%
稀釋每股盈餘 (新台幣元)	0.64		0.50		28%
EBITDA	13,109	22.4%	12,175	24.0%	8%

綜合損益表 – 半導體封裝測試

與上一季比較

(未經會計師查核)



(新台幣百萬元)	Q2 / 2014	%	Q1 / 2014	%	季變化
營業收入淨額:					
封裝	31,792	81.0%	27,787	80.9%	14%
測試	6,600	16.8%	5,785	16.8%	14%
材料直接銷售	874	2.2%	779	2.3%	12%
營業收入淨額合計	39,266	100.0%	34,351	100.0%	14%
營業毛利	10,588	27.0%	8,243	24.0%	28%
營業淨利 (淨損)	5,973	15.2%	4,210	12.3%	42%
稅前淨利 (淨損)	5,779	14.7%	4,038	11.8%	43%
所得稅利益 (費用)	(647)	-1.6%	(570)	-1.7%	
非控制權益	(38)	-0.1%	(30)	-0.1%	
歸屬於本公司業主之淨利	5,094	13.0%	3,438	10.0%	48%
稀釋每股盈餘 (新台幣元)	0.64		0.44		45%
EBITDA	12,055	30.7%	10,148	29.5%	19%

綜合損益表 – 半導體封裝測試

與去年同期比較

(未經會計師查核)

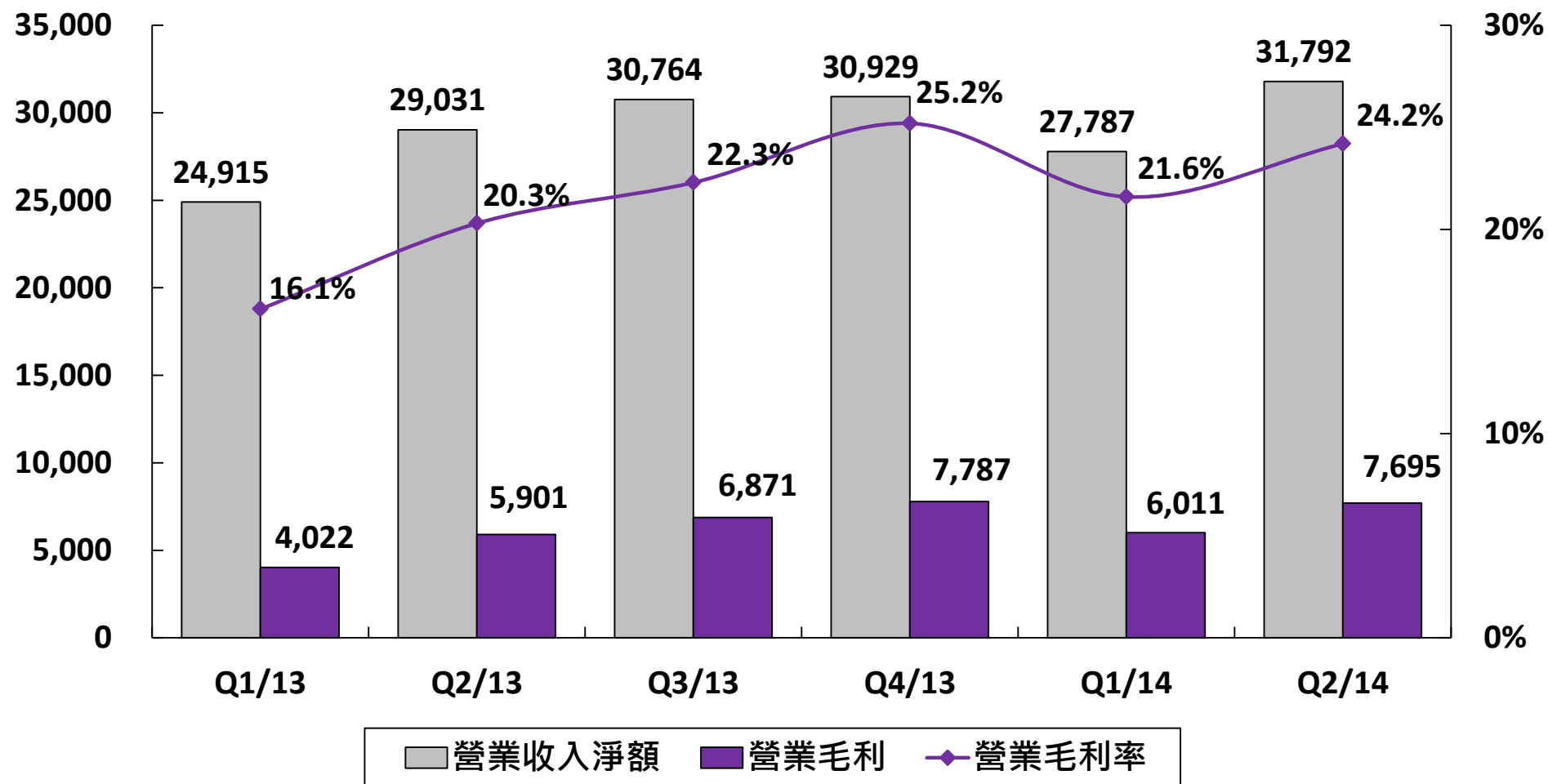


(新台幣百萬元)	Q2 / 2014	%	Q2 / 2013	%	年變化
營業收入淨額:					
封裝	31,792	81.0%	29,031	80.0%	10%
測試	6,600	16.8%	6,505	17.9%	1%
材料直接銷售	874	2.2%	759	2.1%	15%
營業收入淨額合計	39,266	100.0%	36,295	100.0%	8%
營業毛利	10,588	27.0%	8,723	24.0%	21%
營業淨利 (淨損)	5,973	15.2%	4,810	13.3%	24%
稅前淨利 (淨損)	5,779	14.7%	4,833	13.3%	20%
所得稅利益 (費用)	(647)	-1.6%	(975)	-2.7%	
非控制權益	(38)	-0.1%	(38)	-0.1%	
歸屬於本公司業主之淨利	5,094	13.0%	3,820	10.5%	33%
稀釋每股盈餘 (新台幣元)	0.64		0.50		28%
EBITDA	12,055	30.7%	11,095	30.6%	9%

封裝業務

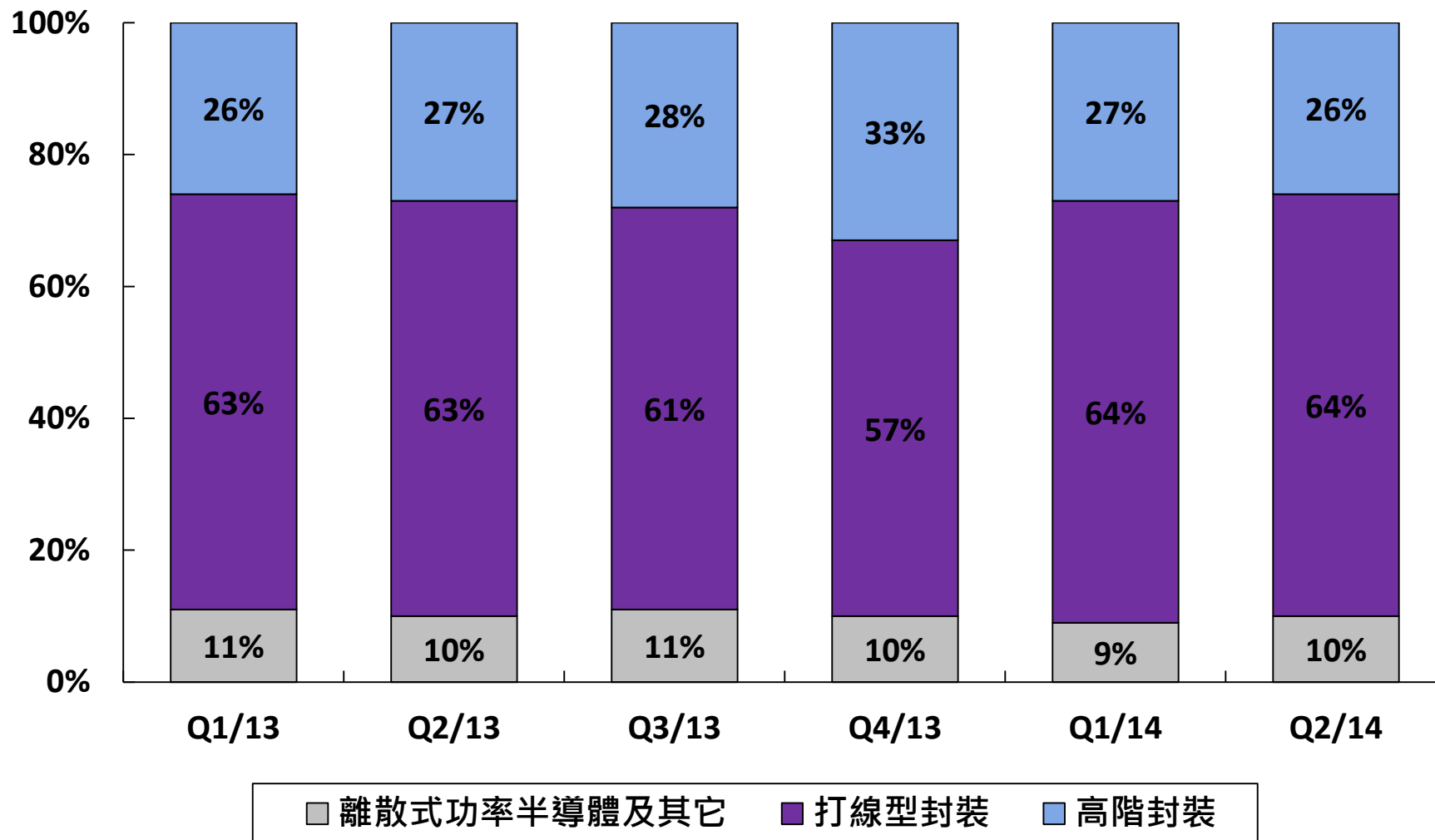


新台幣百萬元



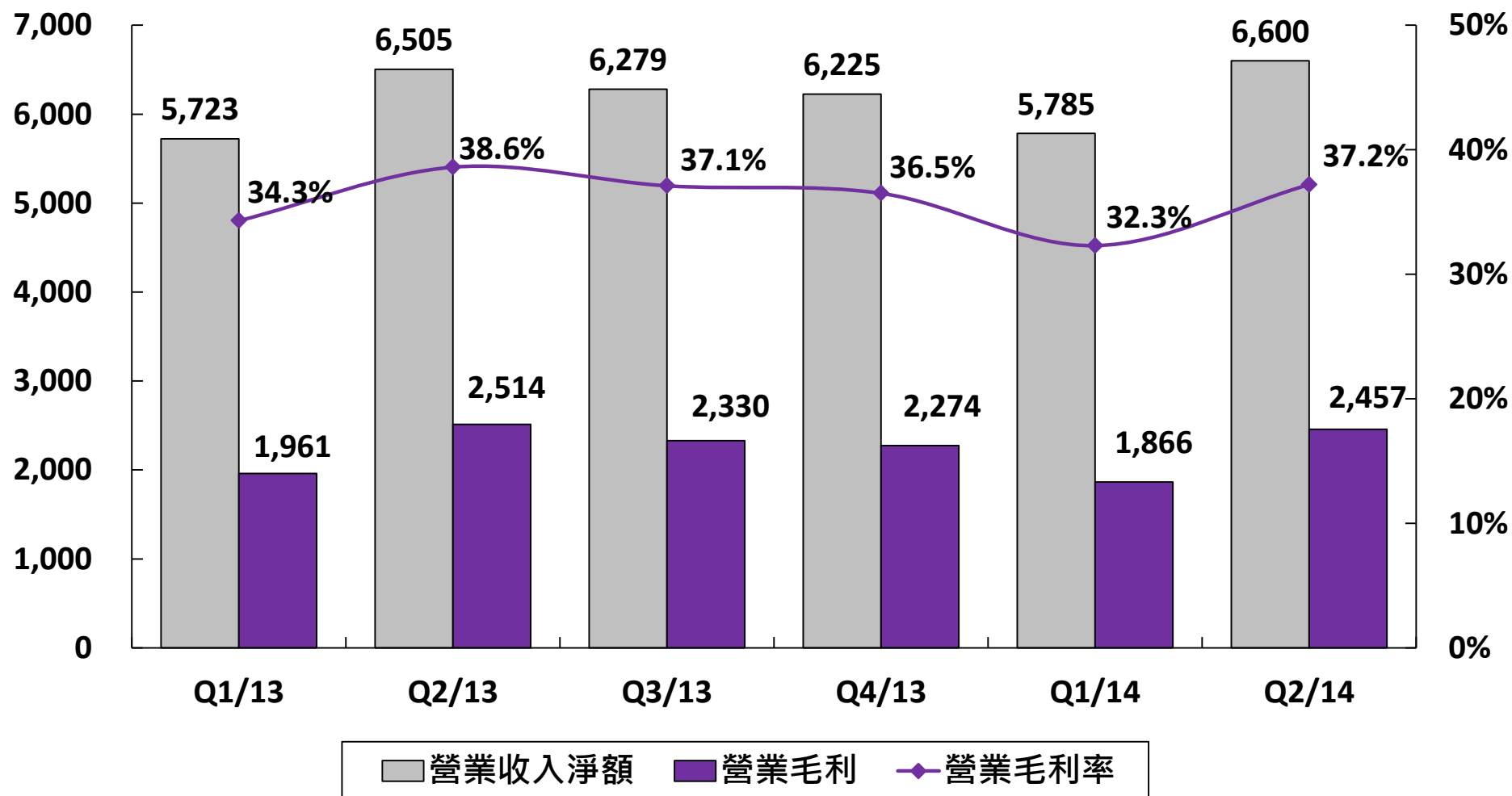
封裝業務

產品組合



測試業務

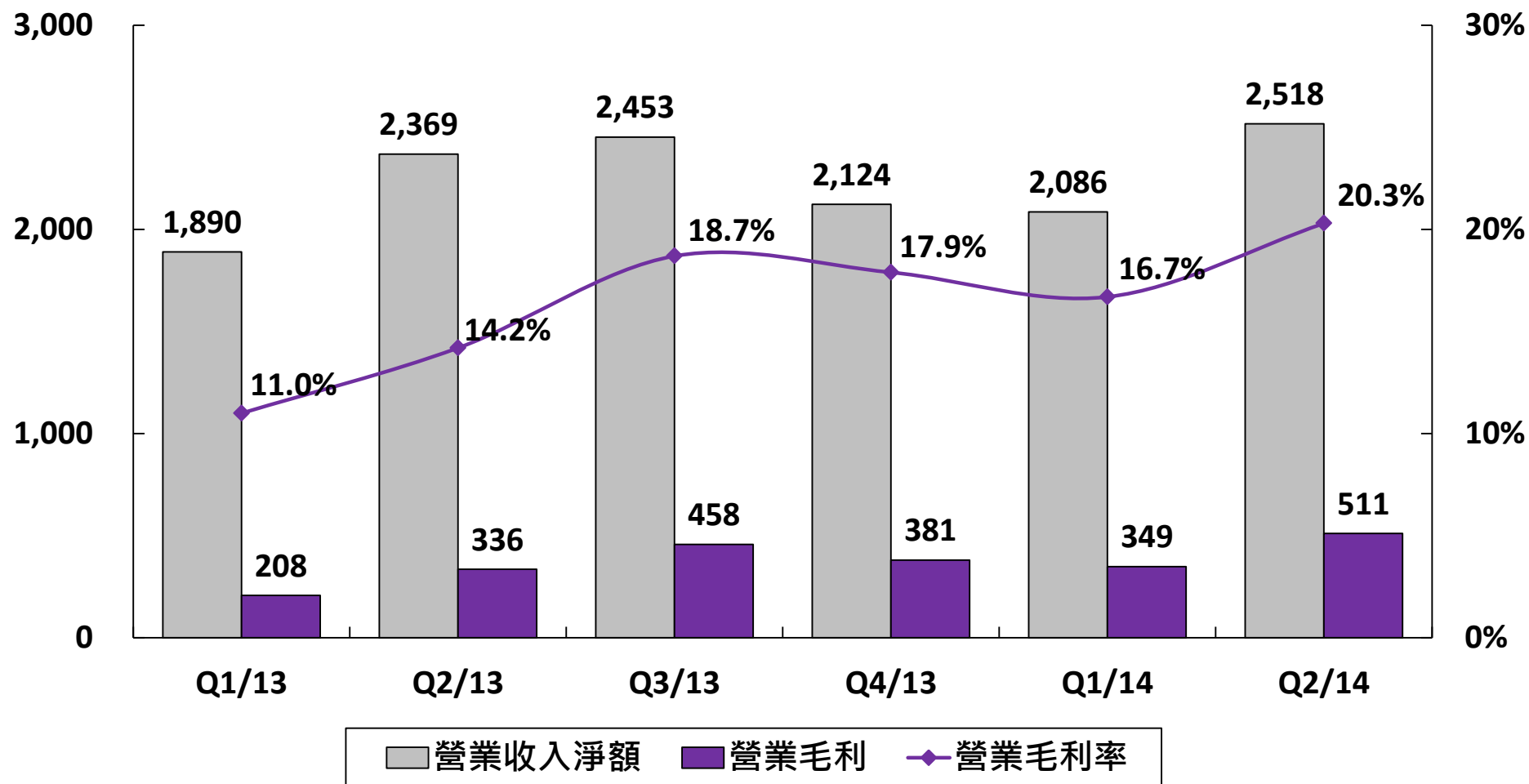
新台幣百萬元



材料業務



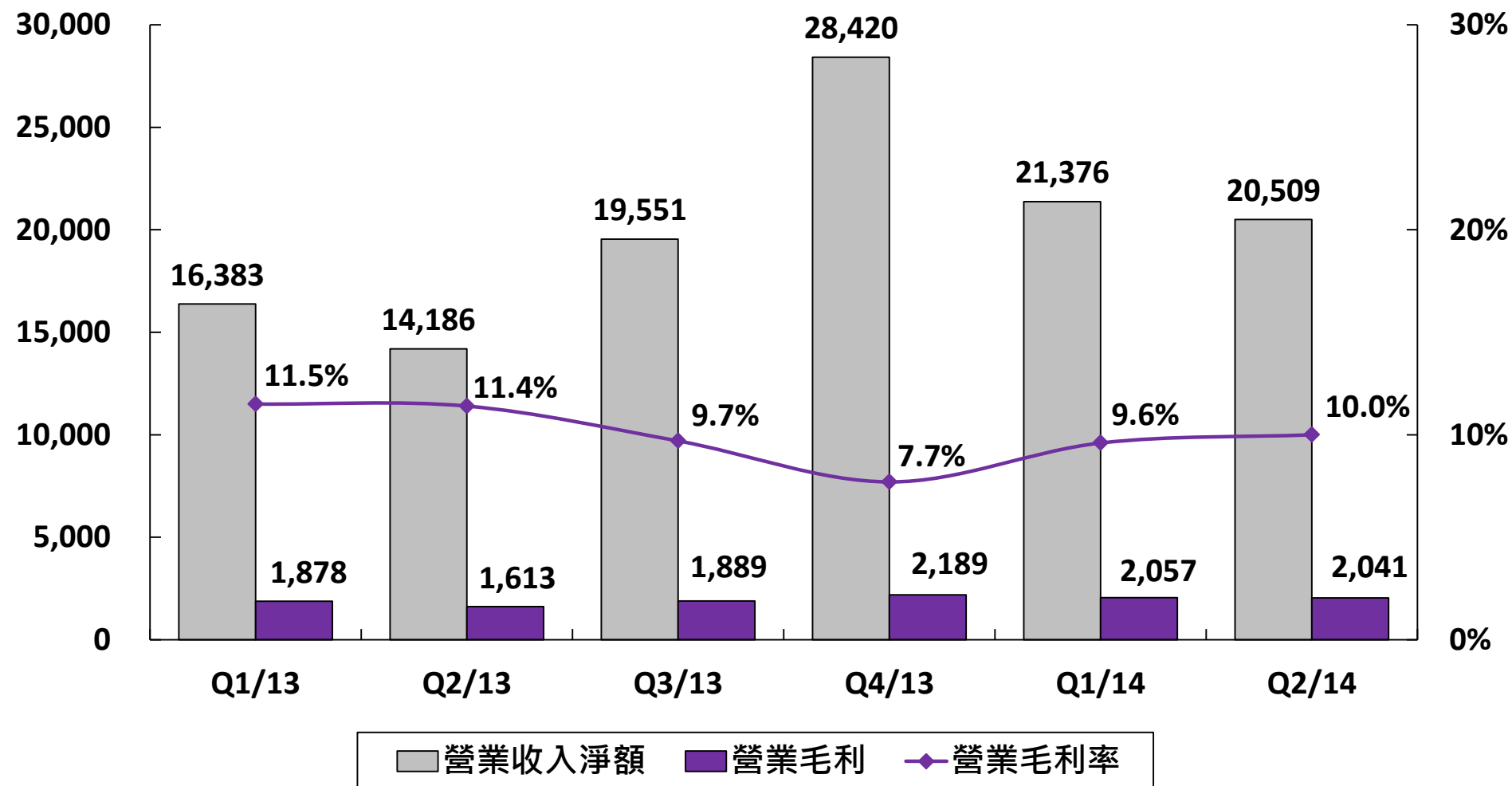
新台幣百萬元



電子代工服務業務

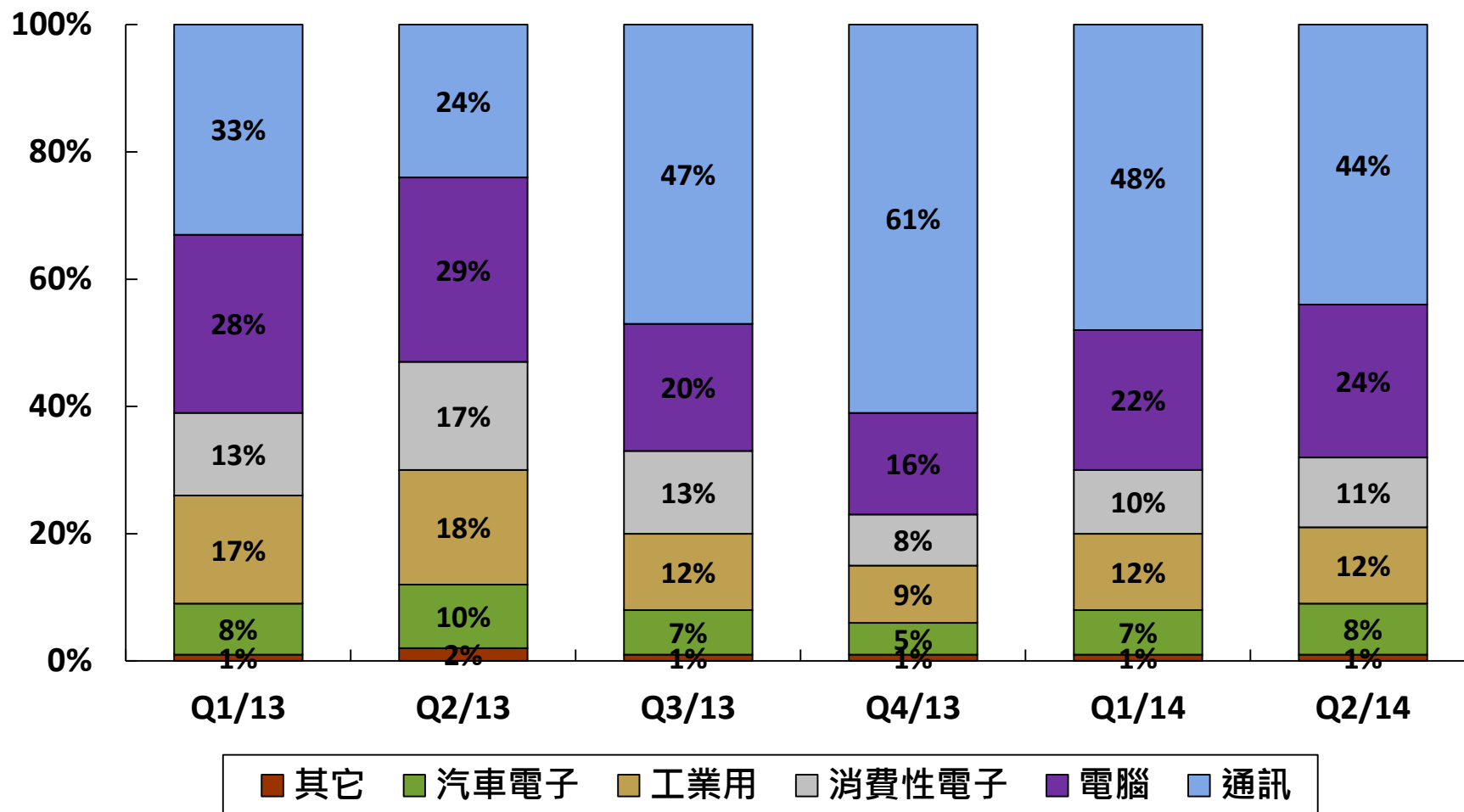


新台幣百萬元



電子代工服務業務

產品應用別



資產負債表及重要財務指標

(未經會計師查核)



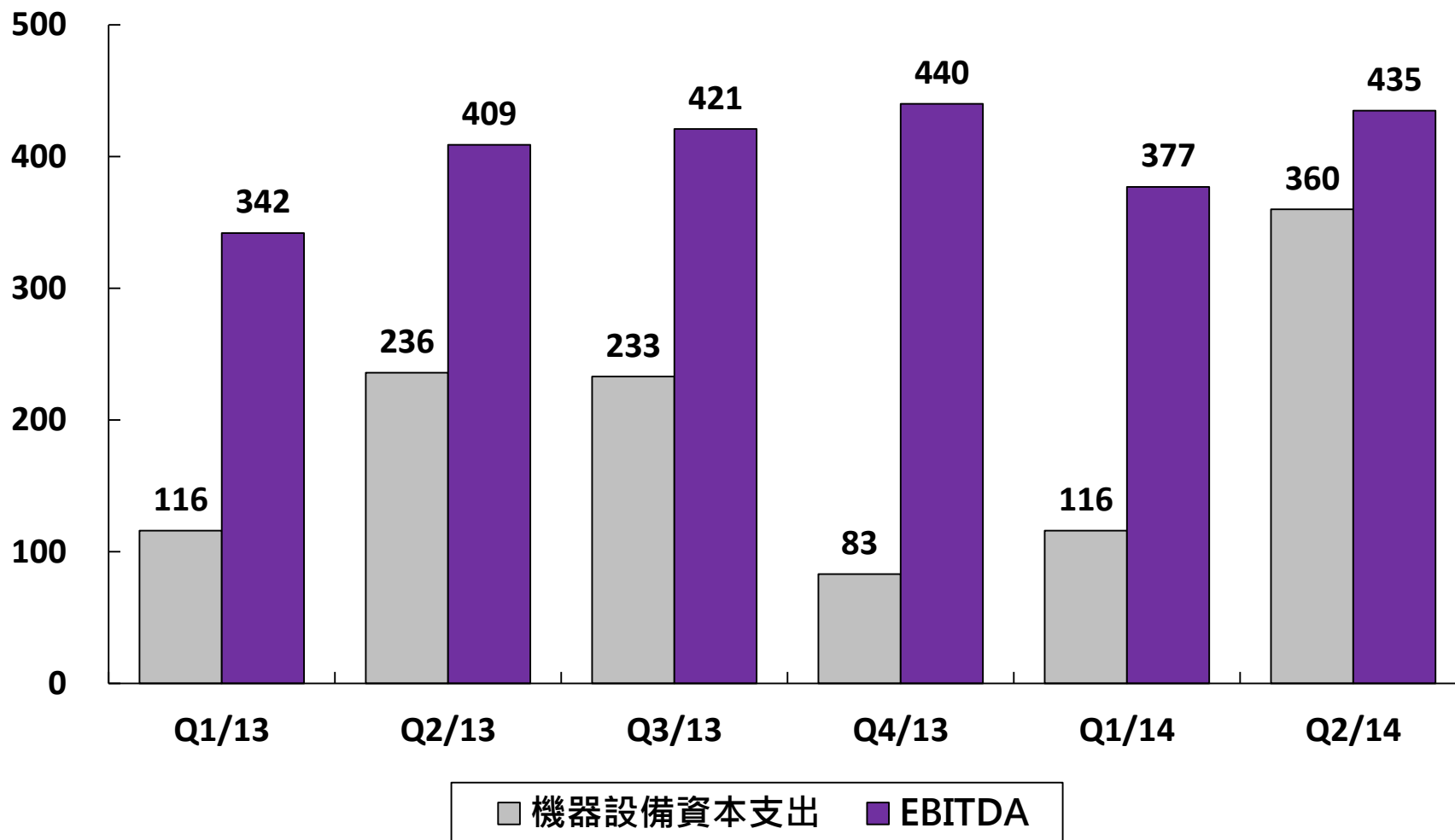
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(新台幣百萬元)	2014年6月30日	2014年3月31日	季變化
現金及約當現金	41,730	43,577	-4.2%
金融資產 - 流動	3,653	5,289	-30.9%
金融資產 - 非流動及採用權益法之投資	2,574	2,609	-1.3%
不動產、廠房及設備	135,555	130,422	3.9%
資產總計	287,600	279,821	2.8%
短期借款	33,281	33,854	-1.7%
一年內到期之應付公司債	728	742	-1.9%
一年內到期之長期借款及應付租賃款	5,316	5,040	5.5%
應付公司債	20,781	20,976	-0.9%
長期借款及應付租賃款	26,940	29,013	-7.1%
權益總計 (含非控制權益)	126,876	133,001	-4.6%
當季 EBITDA	13,109	11,363	15.4%
流動比率	1.23	1.44	
負債權益比率	0.33	0.31	

機器設備資本支出及EBITDA



美金百萬元

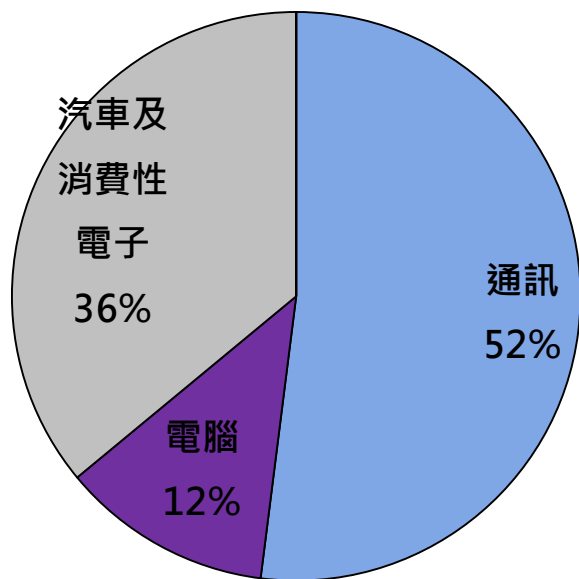


半導體封測營收

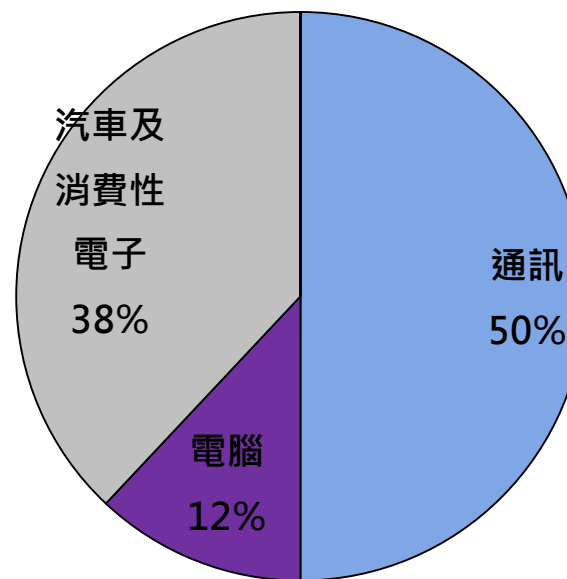
產品應用別佔比



Q1/2014



Q2/2014



2014年第三季業績展望



根據對當前業務狀況的評估及匯率的假設，日月光公司2014年第三季的業績展望如下：

- 半導體封測事業之整體產能將較上一季增加約4%，整體產能利用率將由第二季的80%增加2-4%；
- 電子代工服務第三季營運狀況將延續上半年跟去年同期比較之成長趨勢；
- 合併營業毛利率將小幅度下滑，而合併營業淨利率將略為上升。

Thank You

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